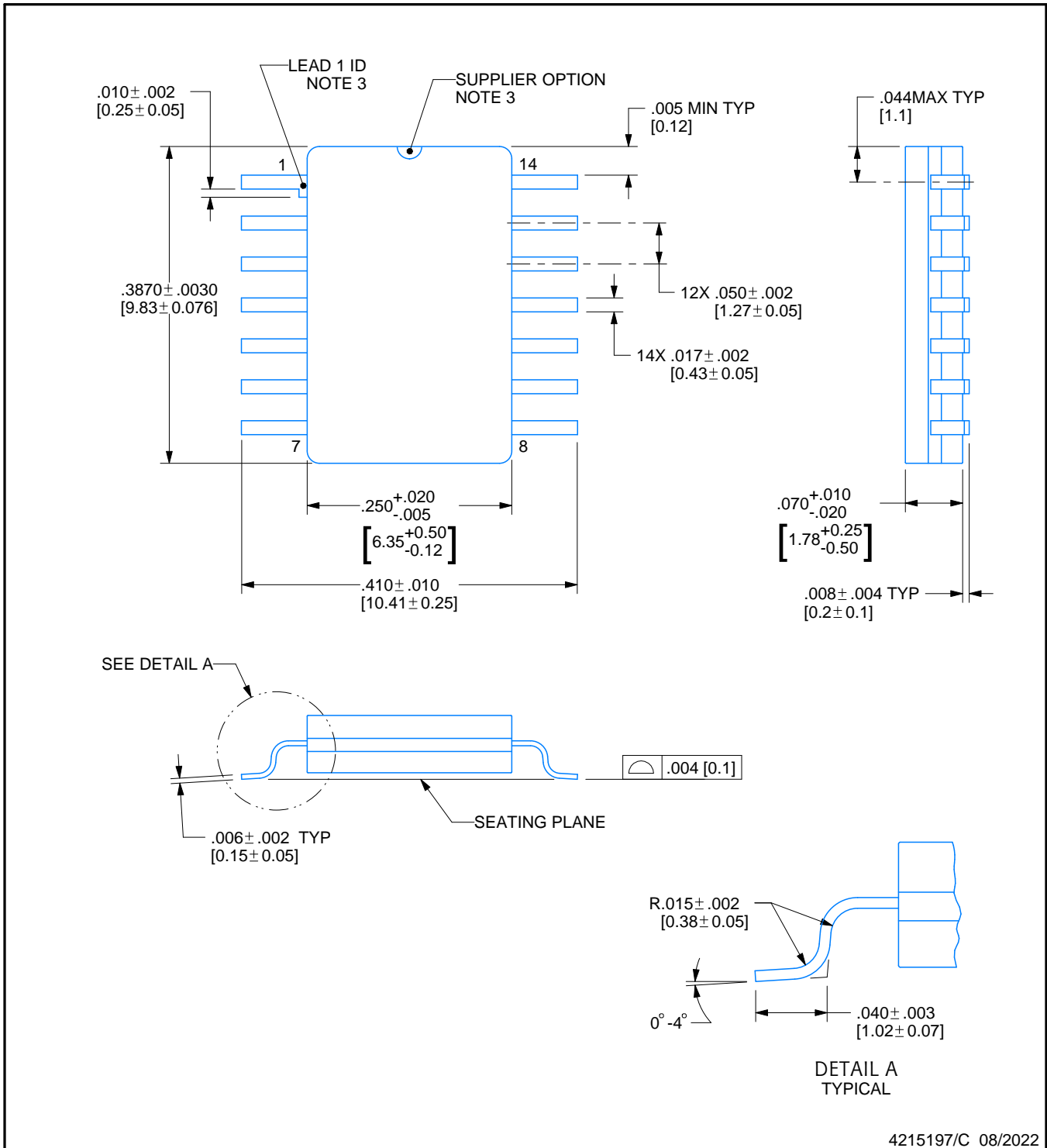


# PACKAGE OUTLINE

## NAC0014A

## CERPACK

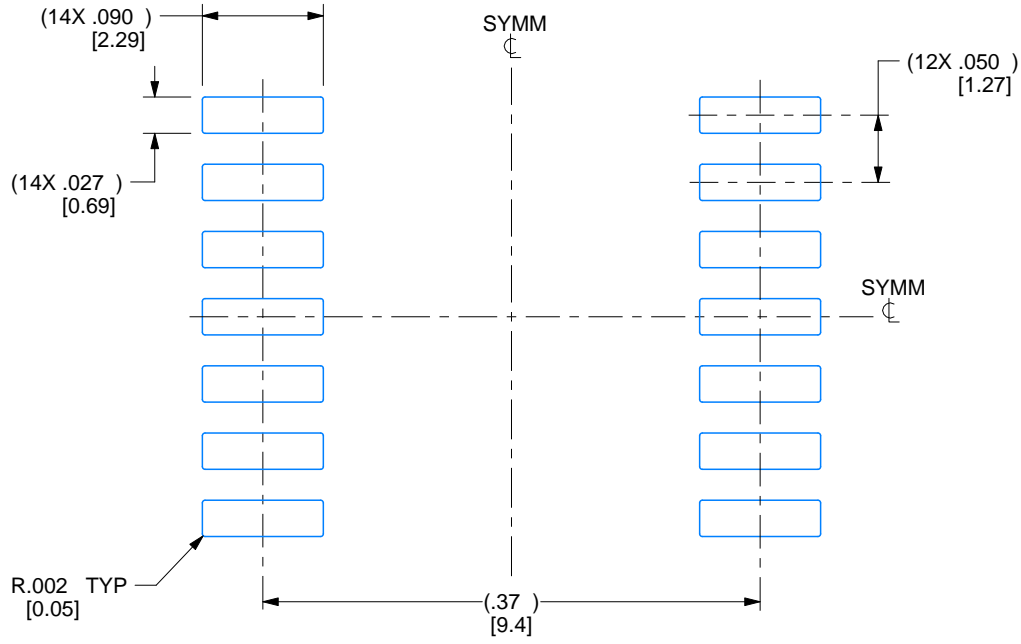
CERAMIC FLATPACK



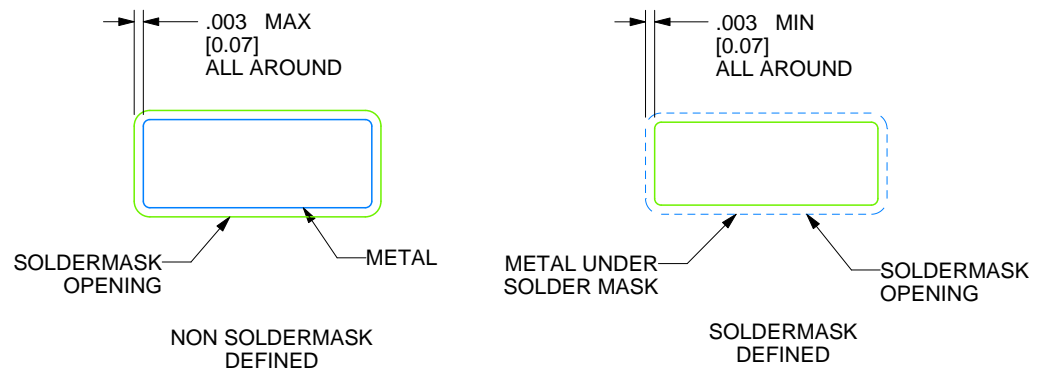
4215197/C 08/2022

### NOTES:

- Controlling dimension is Inch. Values in [ ] are millimeters. Dimensions in ( ) for reference only.
- For solder thickness and composition, see the "Lead Finish Composition/Thickness" link in the packaging section of the Texas Instruments website
- Lead 1 identification shall be:
  - A notch or other mark within this area
  - A tab on lead 1, either side
- No JEDEC registration as of December 2021



RECOMMENDED LAND PATTERN



## REVISIONS

REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	2197878	12/30/2021	DAVID CHIN / ANIS FAUZI
B	NO CHANGE TO DRAWING; REVISION FOR YODA RELEASE;	2198833	02/15/2022	K. SINCERBOX
C	.3870± .0030 WAS .39000± .00012;	2200916	08/08/2022	D. CHIN / K. SINCERBOX

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